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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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##### Details

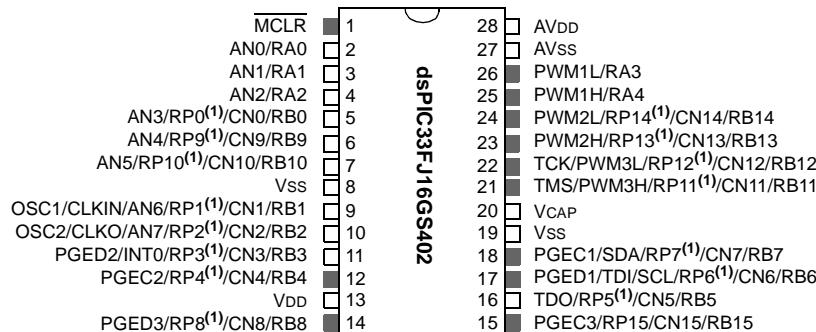
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPS
Connectivity	I <sup>2</sup> C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 24x10b; D/A 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gs504t-i-ml">https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gs504t-i-ml</a>

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

## Pin Diagrams (Continued)

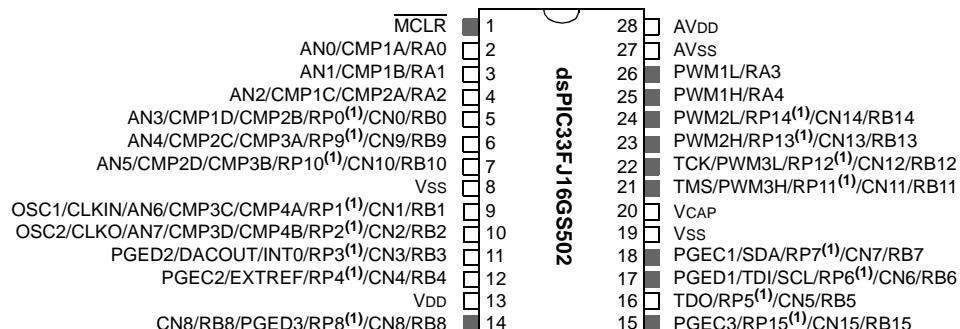
28-Pin SPDIP, SOIC

■ = Pins are up to 5V tolerant



28-Pin SPDIP, SOIC

■ = Pins are up to 5V tolerant



**Note 1:** The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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## REGISTER 3-2: CORCON: CORE CONTROL REGISTER (CONTINUED)

bit 1	<b>RND:</b> Rounding Mode Select bit 1 = Biased (conventional) rounding is enabled 0 = Unbiased (convergent) rounding is enabled
bit 0	<b>IF:</b> Integer or Fractional Multiplier Mode Select bit 1 = Integer mode is enabled for DSP multiply ops 0 = Fractional mode is enabled for DSP multiply ops

**Note 1:** This bit will always read as '0'.

**2:** The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

**TABLE 4-33: PERIPHERAL PIN SELECT INPUT REGISTER MAP**

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPINR0	0680	—	—	INT1R5	INT1R4	INT1R3	INT1R2	INT1R1	INT1R0	—	—	—	—	—	—	—	3F00	
RPINR1	0682	—	—	—	—	—	—	—	—	—	—	INT2R5	INT2R4	INT2R3	INT2R2	INT2R1	INT2R0	003F
RPINR2	0684	—	—	T1CKR5	T1CKR4	T1CKR3	T1CKR2	T1CKR1	T1CKR0	—	—	—	—	—	—	—	0000	
RPINR3	0686	—	—	T3CKR5	T3CKR4	T3CKR3	T3CKR2	T3CKR1	T3CKR0	—	—	T2CKR5	T2CKR4	T2CKR3	T2CKR2	T2CKR1	T2CKR0	3F3F
RPINR7	068E	—	—	IC2R5	IC2R4	IC2R3	IC2R2	IC2R1	IC2R0	—	—	IC1R5	IC1R4	IC1R3	IC1R2	IC1R1	IC1R0	3F3F
RPINR11	0696	—	—	—	—	—	—	—	—	—	—	OCFAR5	OCFAR4	OCFAR3	OCFAR2	OCFAR1	OCFAR0	3F3F
RPINR18	06A4	—	—	U1CTSR5	U1CTSR4	U1CTSR3	U1CTSR2	U1CTSR1	U1CTSR0	—	—	U1RXR5	U1RXR4	U1RXR3	U1RXR2	U1RXR1	U1RXR0	003F
RPINR20	06A8	—	—	SCK1R5	SCK1R4	SCK1R3	SCK1R2	SCK1R1	SCK1R0	—	—	SDI1R5	SDI1R4	SDI1R3	SDI1R2	SDI1R1	SDI1R0	3F3F
RPINR21	06AA	—	—	—	—	—	—	—	—	—	—	SS1R5	SS1R54	SS1R3	SS1R2	SS1R1	SS1R0	0000
RPINR29	06BA	—	—	FLT1R5	FLT1R4	FLT1R3	FLT1R2	FLT1R1	FLT1R0	—	—	—	—	—	—	—	3F00	
RPINR30	06BC	—	—	FLT3R5	FLT3R4	FLT3R3	FLT3R2	FLT3R1	FLT3R0	—	—	FLT2R5	FLT2R4	FLT2R3	FLT2R2	FLT2R1	FLT2R0	3F3F
RPINR31	06BE	—	—	FLT5R5	FLT5R4	FLT5R3	FLT5R2	FLT5R1	FLT5R0	—	—	FLT4R5	FLT4R4	FLT4R3	FLT4R2	FLT4R1	FLT4R0	3F3F
RPINR32	06C0	—	—	FLT7R5	FLT7R4	FLT7R3	FLT7R2	FLT7R1	FLT7R0	—	—	FLT6R5	FLT6R4	FLT6R3	FLT6R2	FLT6R1	FLT6R0	3F3F
RPINR33	06C2	—	—	SYNC1R5	SYNC1R4	SYNC1R3	SYNC1R2	SYNC1R1	SYNC1R0	—	—	FLT8R5	FLT8R4	FLT8R3	FLT8R2	FLT8R1	FLT8R0	3F3F
RPINR34	06C4	—	—	—	—	—	—	—	—	—	—	SYNC1R5	SYNC1R4	SYNC1R3	SYNC1R2	SYNC1R1	SYNC1R0	3F3F

Legend:  $\times$  = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

**TABLE 4-34: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33FJ06GS101**

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	06D0	—	—	RP1R5	RP1R4	RP1R3	RP1R2	RP1R1	RP1R0	—	—	RP0R5	RP0R4	RP0R3	RP0R2	RP0R1	RP0R0	0000
RPOR1	06D2	—	—	RP3R5	RP3R4	RP3R3	RP3R2	RP3R1	RP3R0	—	—	RP2R5	RP2R4	RP2R3	RP2R2	RP2R1	RP2R0	0000
RPOR2	06D4	—	—	RP5R5	RP5R4	RP5R3	RP5R2	RP5R1	RP5R0	—	—	RP4R5	RP4R4	RP4R3	RP4R2	RP4R1	RP4R0	0000
RPOR3	06D6	—	—	RP7R5	RP7R4	RP7R3	RP7R2	RP7R1	RP7R0	—	—	RP6R5	RP6R4	RP6R3	RP6R2	RP6R1	RP6R0	0000
RPOR16	06F0	—	—	RP33R5	RP33R4	RP33R3	RP33R2	RP33R1	RP33R0	—	—	RP32R5	RP32R4	RP32R3	RP32R2	RP32R1	RP32R0	0000
RPOR17	06F2	—	—	RP35R5	RP35R4	RP35R3	RP35R2	RP35R1	RP35R0	—	—	RP34R5	RP34R4	RP34R3	RP34R2	RP34R1	RP34R0	0000

Legend:  $\times$  = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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## REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER<sup>(1,2)</sup> (CONTINUED)

bit 3	<b>CF:</b> Clock Fail Detect bit (read/clear by application) 1 = FSCM has detected clock failure 0 = FSCM has not detected clock failure
bit 2-1	<b>Unimplemented:</b> Read as '0'
bit 0	<b>OSWEN:</b> Oscillator Switch Enable bit 1 = Request oscillator switch to selection specified by NOSC<2:0> bits 0 = Oscillator switch is complete

- Note 1:** Writes to this register require an unlock sequence. Refer to “**Oscillator (Part IV)**” (DS70307) in the “*dsPIC33F/PIC24H Family Reference Manual*” (available from the Microchip web site) for details.
- 2:** This register is reset only on a Power-on Reset (POR).
- 3:** Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

## 15.0 HIGH-SPEED PWM

**Note 1:** This data sheet summarizes the features of the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**High-Speed PWM**” (DS70323) in the “*dsPIC33F/PIC24H Family Reference Manual*”, which is available on the Microchip web site ([www.microchip.com](http://www.microchip.com)).

- 2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The high-speed PWM module on the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 devices supports a wide variety of PWM modes and output formats. This PWM module is ideal for power conversion applications, such as:

- AC/DC Converters
- DC/DC Converters
- Power Factor Correction (PFC)
- Uninterruptible Power Supply (UPS)
- Inverters
- Battery Chargers
- Digital Lighting

### 15.1 Features Overview

The high-speed PWM module incorporates the following features:

- 2-4 PWM generators with 4-8 outputs
- Individual time base and duty cycle for each of the eight PWM outputs
- Dead time for rising and falling edges
- Duty cycle resolution of 1.04 ns
- Dead-time resolution of 1.04 ns
- Phase-shift resolution of 1.04 ns
- Frequency resolution of 1.04 ns
- PWM modes supported:
  - Standard Edge-Aligned
  - True Independent Output
  - Complementary
  - Center-Aligned
  - Push-Pull
  - Multiphase
  - Variable Phase
  - Fixed Off-Time
  - Current Reset
  - Current-Limit

- Independent Fault/Current-Limit inputs for each of the eight PWM outputs
- Output override control
- Special Event Trigger
- PWM capture feature
- Prescaler for input clock
- Dual trigger from PWM to ADC
- PWMxH, PWMxL output pin swapping
- PWM4H, PWM4L pins remappable
- On-the-fly PWM frequency, duty cycle and phase-shift changes
- Disabling of Individual PWM generators to reduce power consumption
- Leading-Edge Blanking (LEB) functionality

**Note:** Duty cycle, dead time, phase shift and frequency resolution is 8.32 ns in Center-Aligned PWM mode.

Figure 15-1 conceptualizes the PWM module in a simplified block diagram. Figure 15-2 illustrates how the module hardware is partitioned for each PWM output pair for the Complementary PWM mode. Each functional unit of the PWM module is discussed in subsequent sections.

The PWM module contains four PWM generators. The module has up to eight PWM output pins: PWM1H, PWM1L, PWM2H, PWM2L, PWM3H, PWM3L, PWM4H and PWM4L. For complementary outputs, these eight I/O pins are grouped into H/L pairs.

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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## REGISTER 15-11: DTRx: PWMx DEAD-TIME REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
—	—			DTRx<13:8>						
bit 15				bit 8						

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
				DTRx<7:0>						
bit 7				bit 0						

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-14      **Unimplemented:** Read as '0'

bit 13-0      **DTRx<13:0>:** Unsigned 14-Bit Dead-Time Value for PWMx Dead-Time Unit bits

## REGISTER 15-12: ALTDTRx: PWMx ALTERNATE DEAD-TIME REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
—	—			ALTDTRx<13:8>						
bit 15				bit 8						

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
				ALTDTR <7:0>						
bit 7				bit 0						

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-14      **Unimplemented:** Read as '0'

bit 13-0      **ALTDTRx<13:0>:** Unsigned 14-Bit Dead-Time Value for PWMx Dead-Time Unit bits

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

## REGISTER 15-13: TRGCONx: PWMx TRIGGER CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
TRGDIV3	TRGDIV2	TRGDIV1	TRGDIV0	—	—	—	—
bit 15	bit 8						

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DTM <sup>(1)</sup>	—	TRGSTRT5	TRGSTRT4	TRGSTRT3	TRGSTRT2	TRGSTRT1	TRGSTRT0
bit 7	bit 0						

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-12	<b>TRGDIV&lt;3:0&gt;</b> : Trigger # Output Divider bits  1111 = Trigger output for every 16th trigger event 1110 = Trigger output for every 15th trigger event 1101 = Trigger output for every 14th trigger event 1100 = Trigger output for every 13th trigger event 1011 = Trigger output for every 12th trigger event 1010 = Trigger output for every 11th trigger event 1001 = Trigger output for every 10th trigger event 1000 = Trigger output for every 9th trigger event 0111 = Trigger output for every 8th trigger event 0110 = Trigger output for every 7th trigger event 0101 = Trigger output for every 6th trigger event 0100 = Trigger output for every 5th trigger event 0011 = Trigger output for every 4th trigger event 0010 = Trigger output for every 3rd trigger event 0001 = Trigger output for every 2nd trigger event 0000 = Trigger output for every trigger event
bit 11-8	<b>Unimplemented</b> : Read as '0'
bit 7	<b>DTM</b> : Dual Trigger Mode bit <sup>(1)</sup>  1 = Secondary trigger event is combined with the primary trigger event to create the PWM trigger. 0 = Secondary trigger event is not combined with the primary trigger event to create the PWM trigger; two separate PWM triggers are generated
bit 6	<b>Unimplemented</b> : Read as '0'
bit 5-0	<b>TRGSTRT&lt;5:0&gt;</b> : Trigger Postscaler Start Enable Select bits  111111 = Wait 63 PWM cycles before generating the first trigger event after the module is enabled • • • 000010 = Wait 1 PWM cycles before generating the first trigger event after the module is enabled 000001 = Wait 1 PWM cycle before generating the first trigger event after the module is enabled 000000 = Wait 0 PWM cycles before generating the first trigger event after the module is enabled

**Note 1:** The secondary generator cannot generate PWM trigger interrupts.

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

## REGISTER 15-16: TRIGx: PWMx PRIMARY TRIGGER COMPARE VALUE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
TRGCMP<7:3>							
bit 7							bit 0

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-3      **TRGCMP<15:3>**: Trigger Control Value bits

When primary PWM functions in the local time base, this register contains the compare values that can trigger the ADC module.

bit 2-0      **Unimplemented**: Read as '0'

## REGISTER 15-17: STRIGx: PWMx SECONDARY TRIGGER COMPARE VALUE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STRGCMP<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
STRGCMP<7:3>							
bit 7							bit 0

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-3      **STRGCMP<15:3>**: Secondary Trigger Control Value bits

When secondary PWM functions in the local time base, this register contains the compare values that can trigger the ADC module.

bit 2-0      **Unimplemented**: Read as '0'

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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**TABLE 21-2: dsPIC33F CONFIGURATION BITS DESCRIPTION**

Bit Field	Register	RTSP Effect	Description
BWRP	FBS	Immediate	Boot Segment Program Flash Write Protection bit 1 = Boot segment can be written 0 = Boot segment is write-protected
BSS<2:0>	FBS	Immediate	Boot Segment Program Flash Code Protection Size bits x11 = No boot program Flash segment <u>Boot Space is 256 Instruction Words (except interrupt vectors):</u> 110 = Standard security; boot program Flash segment ends at 0x0003FE 010 = High security; boot program Flash segment ends at 0x0003FE <u>Boot Space is 768 Instruction Words (except interrupt vectors):</u> 101 = Standard security; boot program Flash segment ends at 0x0007FE 001 = High security; boot program Flash segment ends at 0x0007FE <u>Boot Space is 1792 Instruction Words (except interrupt vectors):</u> 100 = Standard security; boot program Flash segment ends at 0x000FFE 000 = High security; boot program Flash segment ends at 0x000FFE
GSS<1:0>	FGS	Immediate	General Segment Code-Protect bits 11 = User program memory is not code-protected 10 = Standard security 0x = High security
GWRP	FGS	Immediate	General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
IESO	FOSCSEL	Immediate	Two-speed Oscillator Start-up Enable bit 1 = Start-up device with FRC, then automatically switch to the user-selected oscillator source when ready 0 = Start-up device with user-selected oscillator source
FNOSC<2:0>	FOSCSEL	If clock switch is enabled, RTSP effect is on any device Reset; otherwise, Immediate	Initial Oscillator Source Selection bits 111 = Internal Fast RC (FRC) Oscillator with Postscaler 110 = Internal Fast RC (FRC) Oscillator with Divide-by-16 101 = LPRC Oscillator 100 = Reserved 011 = Primary (XT, HS, EC) Oscillator with PLL 010 = Primary (XT, HS, EC) Oscillator 001 = Internal Fast RC (FRC) Oscillator with PLL 000 = FRC Oscillator
FCKSM<1:0>	FOSC	Immediate	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
IOL1WAY	FOSC	Immediate	Peripheral Pin Select Configuration bit 1 = Allows only one reconfiguration 0 = Allows multiple reconfigurations
OSCIOFNC	FOSC	Immediate	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is the clock output 0 = OSC2 is the general purpose digital I/O pin

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

**TABLE 22-2: INSTRUCTION SET OVERVIEW (CONTINUED)**

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
48	MPY	MPY Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	Multiply Wm by Wn to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		MPY Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	Square Wm to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
49	MPY.N	MPY.N Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	-(Multiply Wm by Wn) to Accumulator	1	1	None
50	MSC	MSC Wm*Wm,Acc,Wx,Wxd,Wy,Wyd ,AWB	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
51	MUL	MUL.SS Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		MUL.SU Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.US Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.UU Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL f	W3:W2 = f * WREG	1	1	None
52	NEG	NEG Acc	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG f	f = $\bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG f,WREG	WREG = $\bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG Ws,Wd	Wd = $\bar{Ws} + 1$	1	1	C,DC,N,OV,Z
53	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
54	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
55	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
56	PWRSAV	PWRSAV #lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
57	RCALL	RCALL Expr	Relative Call	1	2	None
		RCALL Wn	Computed Call	1	2	None
58	REPEAT	REPEAT #lit14	Repeat Next Instruction lit14 + 1 times	1	1	None
		REPEAT Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
59	RESET	RESET	Software Device Reset	1	1	None
60	RETFIE	RETFIE	Return from interrupt	1	3 (2)	None
61	RETLW	RETLW #lit10,Wn	Return with Literal in Wn	1	3 (2)	None
62	RETURN	RETURN	Return from Subroutine	1	3 (2)	None
63	RLC	RLC f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
64	RLNC	RLNC f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z
65	RRC	RRC f	f = Rotate Right through Carry f	1	1	C,N,Z
		RRC f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z
		RRC Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z

## 23.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

## 23.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

## 23.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

## 23.9 PICkit 3 In-Circuit Debugger/Programmer

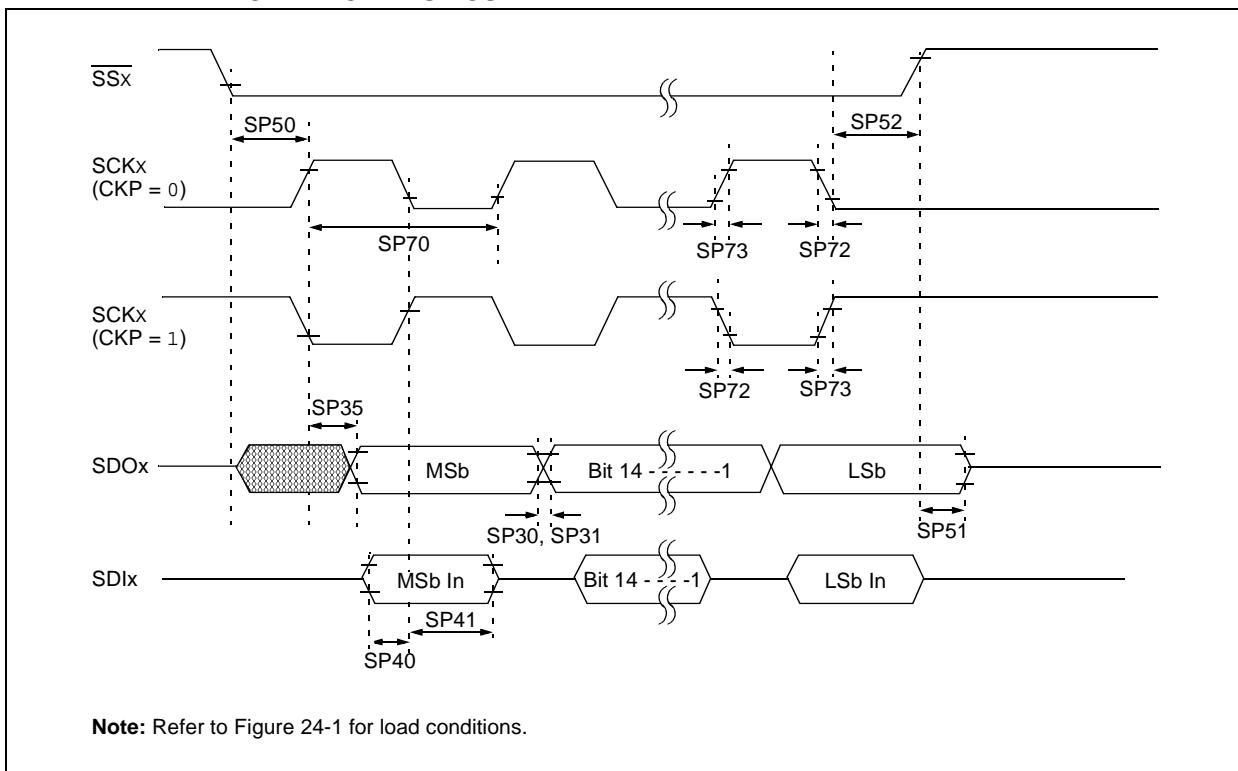
The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

## 23.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

**FIGURE 24-18: SPI<sub>x</sub> SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS**



# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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**TABLE 24-42: COMPARATOR MODULE SPECIFICATIONS**

DC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 3.0V to 3.6V Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	Symbol	Characteristic	Min	Typ	Max	Units	Comments
CM10	VIOFF	Input Offset Voltage	-58	+14/-40	66	mV	
CM11	VICM	Input Common-Mode Voltage Range <sup>(1)</sup>	0	—	AVDD – 1.5	V	
CM12	VGAIN	Open Loop Gain <sup>(1)</sup>	90	—	—	db	
CM13	CMRR	Common-Mode Rejection Ratio <sup>(1)</sup>	70	—	—	db	
CM14	TRESP	Large Signal Response	21	30	49	ns	V+ input step of 100 mv while V- input held at AVDD/2. Delay measured from analog input pin to PWM output pin.

**Note 1:** Parameters are for design guidance only and are not tested in manufacturing.

**2:** Module is functional at VBOR < VDD < VDDMIN, but with degraded performance. Module functionality is tested but not characterized.

**TABLE 24-43: DAC MODULE SPECIFICATIONS**

AC and DC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 3.0V to 3.6V Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	Symbol	Characteristic	Min	Typ	Max	Units	Comments
DA01	EXTREF	External Voltage Reference <sup>(1)</sup>	0		AVDD – 1.6	V	
DA08	INTREF	Internal Voltage Reference <sup>(1)</sup>	1.25	1.32	1.41	V	
DA02	CVRES	Resolution	10			Bits	
DA03	INL	Integral Nonlinearity Error	-7	-1	+7	LSB	AVDD = 3.3V, DACREF = (AVDD/2)V
DA04	DNL	Differential Nonlinearity Error	-5	-0.5	+5	LSB	
DA05	EOFF	Offset Error	0.4	-0.8	2.6	%	
DA06	EG	Gain Error	0.4	-1.8	5.2	%	
DA07	TSET	Settling Time <sup>(1)</sup>	711	1551	2100	nsec	Measured when range = 1 (high range), and CMREF<9:0> transitions from 0x1FF to 0x300.

**Note 1:** Parameters are for design guidance only and are not tested in manufacturing.

**2:** Module is functional at VBOR < VDD < VDDMIN, but with degraded performance. Module functionality is tested but not characterized.

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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**TABLE 25-9: SPI<sub>x</sub> MASTER MODE (CKE = 0) TIMING REQUIREMENTS**

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Symbol	Characteristic <sup>(1)</sup>	Min	Typ	Max	Units	Conditions
HSP35	Tsch2doV, TscL2doV	SDO <sub>x</sub> Data Output Valid after SCK <sub>x</sub> Edge	—	10	25	ns	
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCK <sub>x</sub> Edge	28	—	—	ns	
HSP41	Tsch2diL, TscL2diL	Hold Time of SDIx Data Input to SCK <sub>x</sub> Edge	35	—	—	ns	

**Note 1:** These parameters are characterized but not tested in manufacturing.

**TABLE 25-10: SPI<sub>x</sub> MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS**

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Symbol	Characteristic <sup>(1)</sup>	Min	Typ	Max	Units	Conditions
HSP35	Tsch2doV, TscL2doV	SDO <sub>x</sub> Data Output Valid after SCK <sub>x</sub> Edge	—	10	25	ns	
HSP36	TdoV2sc, TdoV2scL	SDO <sub>x</sub> Data Output Setup to First SCK <sub>x</sub> Edge	35	—	—	ns	
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCK <sub>x</sub> Edge	28	—	—	ns	
HSP41	Tsch2diL, TscL2diL	Hold Time of SDIx Data Input to SCK <sub>x</sub> Edge	35	—	—	ns	

**Note 1:** These parameters are characterized but not tested in manufacturing.

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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## 26.1 DC Characteristics

TABLE 26-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temp Range (in °C)	Max MIPS
			dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04
—	3.0-3.6V <sup>(1)</sup>	-40°C to +85°C	50

**Note 1:** Overall functional device operation at  $V_{BORMIN} < VDD < V_{DDMIN}$  is tested but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below  $V_{DDMIN}$ . Refer to Parameter BO10 in Table 24-11 for BOR values.

TABLE 26-2: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

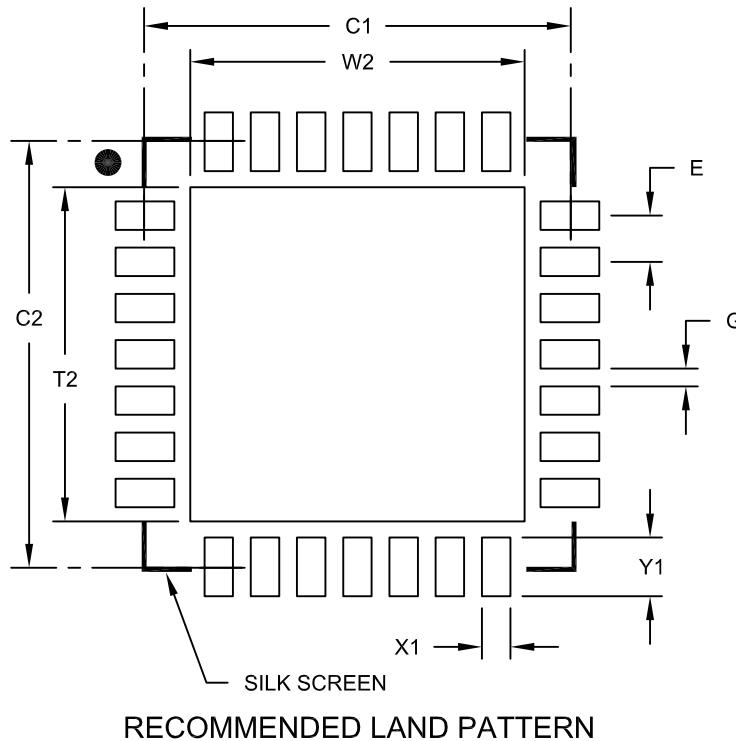
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial			
Parameter No.	Typical	Max	Units	Conditions		
<b>Operating Current (IDD)<sup>(1)</sup></b>						
MDC29d	105	125	mA	-40°C	3.3V	50 MIPS
MDC29a	105	125	mA	+25°C		
MDC29b	105	125	mA	+85°C		

**Note 1:** IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode with PLL, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to Vss
- MCLR = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU executing `while(1)` statement
- JTAG is disabled

## 28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1	6.00		
Contact Pad Spacing	C2	6.00		
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

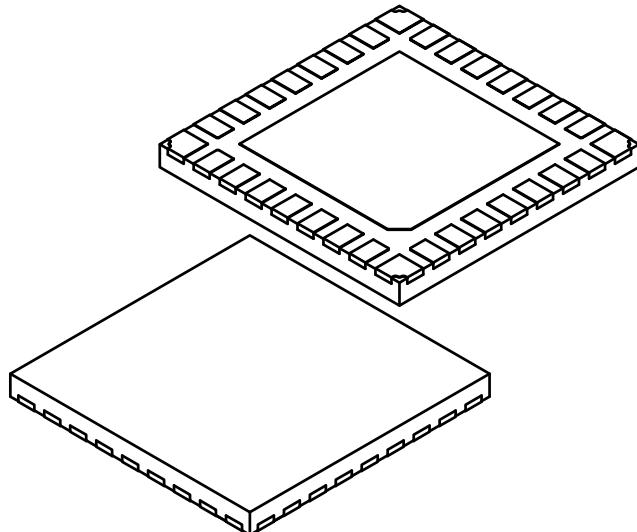
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

## 28-Lead Plastic Quad Flat, No Lead Package (MX) - 6x6x0.5mm Body [UQFN] Ultra-Thin with 0.40 x 0.60 mm Terminal Width/Length and Corner Anchors

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins		N		28
Pitch		e		0.65 BSC
Overall Height		A		0.40    0.50    0.60
Standoff		A1		0.00    0.02    0.05
Terminal Thickness		(A3)		0.127 REF
Overall Width		E		6.00 BSC
Exposed Pad Width		E2		4.00
Overall Length		D		6.00 BSC
Exposed Pad Length		D2		4.00
Terminal Width		b		0.35    0.40    0.45
Corner Pad		b2		0.25    0.40    0.45
Terminal Length		L		0.55    0.60    0.65
Terminal-to-Exposed Pad		K		-

### Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

4. Outermost portions of corner structures may vary slightly.

# dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04

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